506375034 11/30/2020

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT6421790

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
Da-Jun Lin	11/24/2020	
Yi-An Shih	11/24/2020	
Bin-Siang Tsai	11/24/2020	
Fu-Yu Tsai	11/24/2020	

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17106214

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

Address Line 1: 5F., NO.389, FUHE RD., YONGHE DIST.,

Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	NAUP3732USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	11/30/2020

Total Attachments: 8

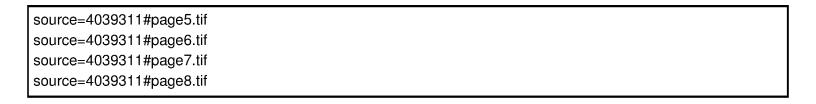
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506375034



Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:				
☑ The attached application, or	-				
☐ United States application number		filed or	_filed on , c		
☐ PCT international application number		filed	l on		
The above-identified application was	made or authorized to b	e made by me.			
I believe that I am the original invent application.	or or an original joint inve	entor of a claimed	invention in the	•	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made ir isonment of not more tha	this declaration n five (5) years, o	is punishable or both.		
In consideration of the payment by	UNITED MICROELE CORP.	CTRONICS	having a postal	address of	
No.3, Li-Hsin Road 2, Science	-Based Industrial Pa	ırk, Hsin-Chu	City 300, Taiv	wan, R.O.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dol nd valuable consideration	ar (\$ 1.00), the re	eceipt of which is	s hereby	
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.					
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;					
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said invention are ecessary or desirable to c	nd said Letters Pa arry out the prope	atent and said		
Note: An application data sheet (PTC	D/SB/14 or equivalent), in	cluding naming t	he entire		

Page 1 of 8

inventive entity, must accompany this form. Use this form for each additional inventor.

NPO#NAU-P3732-USA:0 CUST#UMCD-2020-0336

F#NPO-P0002E-US1201 DSB0-109U033347

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Da-Jun Lin Date: NOV 2 4 2020

Signature: DA-Jun Lin Date: NOV 2 4 2020

NPO#NAU-P3732-USA:0 CUST#UMCD-2020-0336 Page 2 of 8

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I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.				
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement on this assignment;	or encumbrance has	been or will be made	e or
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representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	lication, said inventi cessary or desirable	on and said Letters to carry out the pro	Patent and said poses thereof.	
Note: An application data sheet (PTC	D/SB/14 or equivaler	nt), including naming	the entire	

Page 3 of 8

inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Yi-An Shih

Date:

NOV 2 4 2020

NPO#NAU-P3732-USA:0

CUST#UMCD-2020-0336

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F#NPO-P0002E-US1201 DSB0-109U033347

PATENT

REEL: 054484 FRAME: 0266

Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

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☐ PCT international application nu	ımber	filed on	-		
The above-identified application was ma	de or authorized to be made l	oy me.			
I believe that I am the original inventor or application.	an original joint inventor of a	claimed invention in the			
I hereby acknowledge that any willful fals under18 U.S.C. 1001 by fine or imprison	e statement made in this dec ment of not more than five (5)	laration is punishable years, or both.			
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I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;					
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, instrumaintain, issue and enforce said applicat equivalents thereof which may be necess IN WITNESS WHEREOF, I have hereunt	on, said invention and said L arv or desirable to carry out t	etters Patent and said			
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.					

Page 5 of 8

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Bin-Siang Tsai Date: NOV 2 4 2020

Signature: 15 12 - Story (Sat

NPO#NAU-P3732-USA:0 CUST#UMCD-2020-0336 Page 6 of 8

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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, an	nd to any and all impr ation and, in and to, al r any continuations, co	ovements which are Letters Patent to b ontinuation-in-part,	e disclosed in the le obtained for said divisions, renewals,	
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NPO#NAU-P3732-USA:0 CUST#UMCD-2020-0336 F#NPO-P0002E-US1201 DSB0-109U033347

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Fu-Yu Tsai

Date: NOV 2 4 2020

Signature: Fu-Yu Tsai

NPO#NAU-P3732-USA:0 CUST#UMCD-2020-0336

RECORDED: 11/30/2020

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F#NPO-P0002E-US1201 DSB0-109U033347